

S2058

#### **FEATURES**

- ANSI X3T11 Fibre Channel Compatible
- Monolithic Clock Recovery Unit
  - Re-times & Buffers Received Data
  - Jitter Peaking < 0.15 dB
- Lock Detect Function
  - Run Length Violation Detector
  - Frequency Detection
- Port Bypass Circuit
- Suitable for both Coaxial and Optical Link

#### **APPLICATIONS**

- Low Power Operation 0.425W, Typical
- 106.25 or 53.125 MHz Reference Clock
- 28-Pin SOIC Package
- 3.3V Supply

#### **GENERAL DESCRIPTION**

The Fibre Channel Port Bypass with Repeater Circuit is used in full-speed (1.0625 Gb/s) Disk Arrays. The S2058 block diagram is shown in Figure 1. It contains a monolithic Clock Recovery Unit (CRU), a lock detect feature and a port bypass Circuit. The CRU may be used alone to implement a general purpose Repeater needed for many Disk Array and Switch applications where a re-timed and buffered signal is required. The S2058 may be used to implement a single chip Arbitrated Loop Port Bypass Retiming Node. The S2058 performs the function of a port bypass circuit followed by a clock and data retiming Phase Locked Loop (CDR). The CDR retimes incoming serial data, detects whether a valid signal is present and outputs a low jitter serial data stream.

#### **FUNCTIONAL DESCRIPTION**

The S2058 performs two functions. The first is a Port Bypass Circuit (PBC) for nodes in a FC-AL system. The low jitter accumulation of the Port Bypass Path is essential in these systems. The second function is to retime and restore signal quality in RAID drives using the FC-AL link configuration. The low jitter transfer peaking and the high jitter tolerance specifications of the Clock and Data Recovery PLL are essential in these applications. In addition, the Lock

detect circuit monitors the incoming signals for valid 8B/10B run length, transition density and frequency. The output of this circuit is useful for link performance monitoring and detection of channel present.

#### **Jitter Performance**

The S2058 complies with the minimum jitter tolerance requirements proposed by the Fibre Channel jitter working group when used with differential inputs and outputs as shown in Figure 2. In addition, the S2058 is designed for minimum jitter generation and jitter transfer specifications. This allows the optimum system design for arbitrated loop architectures.

#### **Jitter Tolerance**

Input jitter tolerance is defined as the amplitude of frequency dependent, random and deterministic jitter that causes the clock recovery PLL to violate the BER specifications. Input jitter tolerance specifications are shown in Figures 3 and 4.

Figure 1. S2058 Block Diagram

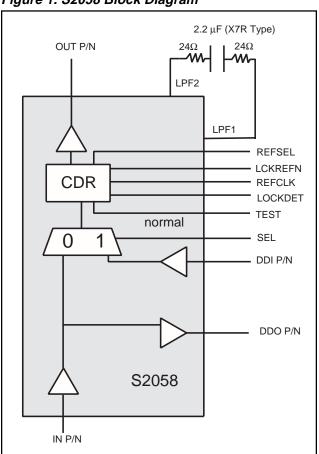
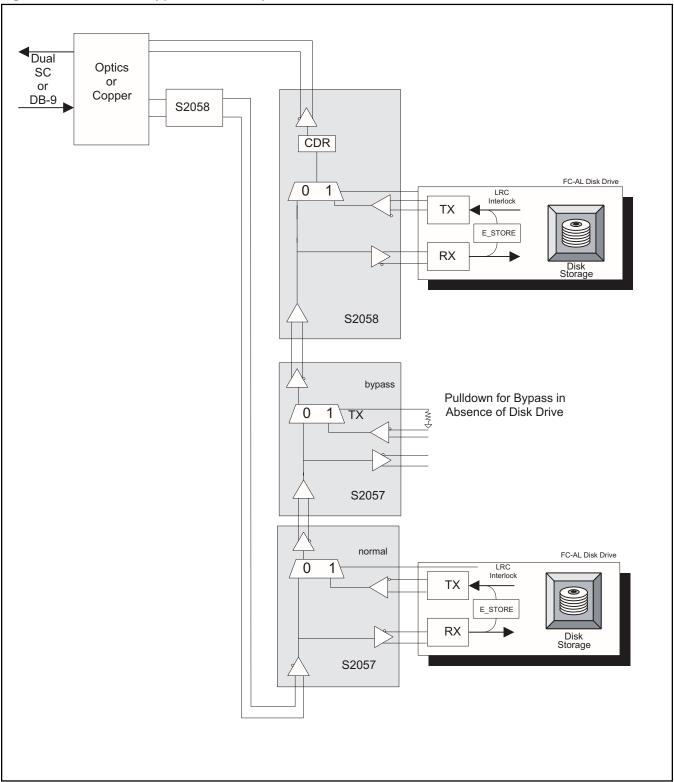




Figure 2. FC-AL JBOD Application for Repeaters





## FREQUENCY DEPENDENT JITTER TOLERANCE

Frequency Dependent Input jitter tolerance is defined as the peak to peak amplitude of sinusoidal jitter applied on the input signal. See Figure 3.

#### **Random Jitter Tolerance**

Random Jitter Tolerance is the amount of jitter with a gaussian distribution that the clock recovery PLL must tolerate.

#### **Deterministic Jitter Tolerance**

Deterministic Jitter Tolerance is the amount of Deterministic jitter that the clock recovery PLL must tolerate.

#### JITTER TRANSFER

Jitter transfer is defined as the ratio of jitter on the output signal to the jitter applied on the input signal versus frequency. Jitter transfer requirements are shown in Figure 5. The measurement condition is that input sinusoidal jitter up to the mask level in Figure 4 is applied and the output jitter is measured for compliance to the mask of Figure 5. The jitter transfer mask includes specifications for both jitter peaking and bandwidth.

### **LOCK DETECT**

The S2058 lock detect circuit monitors the selected input signal to detect the presence of the channel. This is done by monitoring the run length, transition density and frequency content of the incoming data. The frequency monitor circuit checks the difference between the divided down recovered clock and the externally supplied reference clock (REFCLK). If the frequency difference of the recovered clock and the reference clock varies by more than +/- 240 ppm the part will be declared out of lock. In the out of lock state the PLL will lock to the local reference clock and periodically poll the serial data input looking for data with valid frequency content. In this state the LOCKDET output will shift between high and low states, mirroring the PLL as it locks to REFCLK (LOCKDET INACTIVE) and input data (LOCKDET ACTIVE).

Figure 3. Input Jitter Tolerance

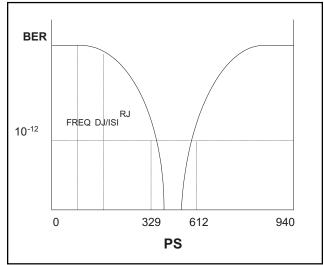


Figure 4. Frequency Dependent Jitter Tolerance Mask

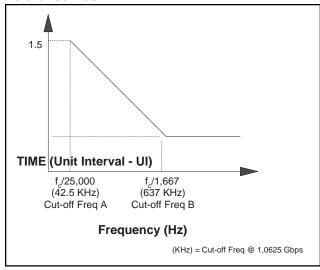


Figure 5. Jitter Transfer Specification

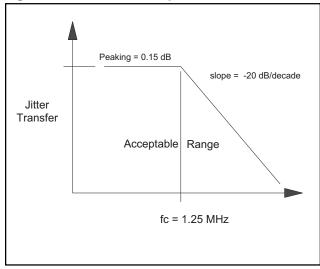


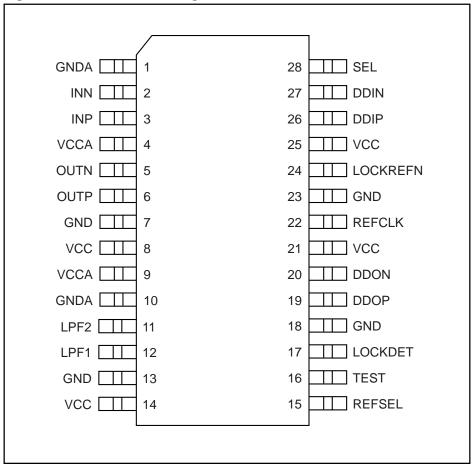


Table 1. Pin Description

Pin Name	Level	I/O	Pin#	Description
OUTP OUTN	Diff. LVPECL	0	6, 5	Serial output to be connected to the next PBC in the loop. (See Figure 2.) This output has been retimed by the clock and data recovery PLL.
INN INP	Diff. LVPECL	I	2, 3	Serial input from the previous Port Bypass Circuit.
DDIP DDIN	Diff. LVPECL	I	26, 27	Serial input to the port bypass. This input should be driven by the FC-AL disk drive connected to the port bypass. This input is routed to the CDR block if the port bypass is in Normal operating mode.
REFCLK	TTL	I	22	Reference clock for the PLL, nominally at 106.25 MHz, rising edge active.
LPF1 LPF2	Analog		12, 11	Loop filter capacitor pins
LCKREFN	3 State TTL	I	24	Active Low. When inactive, the CDR PLL will attempt to lock to input data (normal operation). When active, the CDR PLL will be forced to lock to the local reference clock (REFCLK). When disconnected, the S2058 will be put into test mode and the PLL will be bypassed for factory testing.
LOCKDET	TTL	0	17	Active High. When active, LOCKDET indicates the CDR PLL is locked to the serial data stream. When inactive, the CDR PLL is locked to the local reference clock indicating a loss of data condition. (See Lock Detect section.)
DDON DDOP	LVPECL	0	20, 19	Port bypass output. This output should drive the input port of the FC-AL disk drive.
SEL	TTL	I	28	Port bypass B bypass control. When SELB is Low, the port bypass will be in bypass mode. When SEL is High, port bypass will be in normal mode.
GND	Ground		7, 13, 18, 23	Ground pins are physically mounted to the die surface, and are an important part of the thermal path. For best thermal performance, all ground pins should be connected to a ground plane, using multiple vias if possible.
VCC			8, 14, 21, 25	+3.3V Power supply.
VCCA	Analog		4, 9	+3.3V Power supply for the CRU.
GNDA	Analog		1, 10	Ground for the CRU
TEST	3 Level TTL	I	16	Used for manufacturing test. Normal chip operation when held Low.
REFSEL	TTL	I	15	Active Low. When active allows 106.25 MHz reference clock. When inactive, allows 53.125 MHz clock.



Figure 6. S2058 Pinout Package

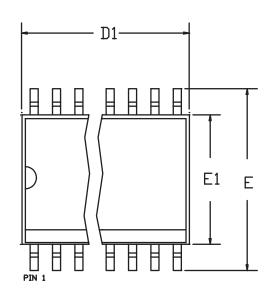


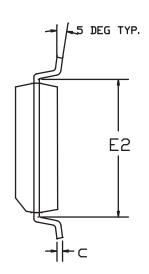
### Thermal Information

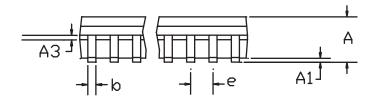
Device	⊖ja (Still Air)		
S2058	53 ° C/W		



Figure 7. S2058 28-SOIC Package







### DIMENSIONS (are in inches)

UNIT	А	A <sub>1</sub>	A <sub>3</sub>	D <sub>1</sub>	E	E <sub>1</sub>	E <sub>2</sub>	е	b	С
MIN	.098	.005		.699	.396	.291	.318			.007
NDM	.101	.008	.010	.704	.406	.294	.328	,050 BASIC	.018 BASIC	.008
MAX	.104	.011		.709	.416	.297	.338			.009

Note: Lead tip coplanarity after form to be within .004



S2058

### Table 2. AC Characteristics

Parameter	Description	Min	Max	Units	Conditions
T <sub>R</sub> , T <sub>F</sub>	REFCLK rise and fall time		3.0	ns	10% to 90%
FT	REFCLK frequency tolerance		100	ppm	Difference between REFCLK and RX data frequency.
DC	REFCLK duty cycle	40/60		%	
Jitter Specif	ications			•	
RJOUT	Random Jitter (RMS) OUT P/N		20	ps	RMS, tested on a sample basis.
DJOUT	Deterministic Jitter (p-p) OUT P/N		50	ps	Peak-to Peak, tested on a sample basis.
FREQJT	Frequency dependent jitter tolerance IN P/N	0.1		UI	Jitter tolerance mask per Fibre Channel Jitter specification.
RANJT	Random jitter tolerance IN P/N		0.22	UI	Peak-toPeak
DJT	Deterministic jitter tolerance IN P/N		0.38	UI	Peak-to-Peak @ >53.125 MHz
JXFR (Input to Output)	Jitter transfer peaking from IN P/N to OUT P/N		0.15	dB	1010 pattern
t <sub>SR</sub> t <sub>SF</sub>	DDO & DOUT		250	ps	20 to 80%



### Table 3. LVTTL DC Characteristics

Parameters	Description	Min	Тур	Max	Units	Conditions
V <sub>OH</sub>	Output High Voltage (TTL)	2.2			V	I <sub>OH</sub> =1 mA
V <sub>OL</sub>	Output Low Voltage (TTL)			0.5	V	I <sub>OL</sub> = +1.2 mA
V <sub>IH</sub>	Input High Voltage (TTL)	2.0			V	
V <sub>IL</sub>	Input Low Voltage (TTL)			0.8	V	
I <sub>IH</sub>	Input High Current (TTL)			50	μΑ	V <sub>IN</sub> = 2.4V
I <sub>IL</sub>	Input Low Current (TTL)	-500		-50	μΑ	V <sub>IN</sub> = 0.5V
$\Delta V_{OUT}$	LVPECL Output differential peak-to-peak voltage swing	1200		2200	mVp-p	50? to V <sub>CC</sub> -2.0V
$\Delta V_{IN}$	Receiver differential peak-to- peak input sensitivity, RX and SI	200		2600	mVp-p	$V_{CC}$ = 3.3V, AC coupled. Internally DC biased to $V_{CC}$ -0.65V

### Table 4. LVPECL Input/Output DC Characteristics

Parameters	Description	Min	Max	Units	Conditions
VOH	Output High Voltage	V <sub>CC</sub> -1.11	V <sub>CC</sub> -0.67	V	
V <sub>OL</sub>	Output Low Voltage	V <sub>CC</sub> -2	V <sub>CC</sub> -1.3	V	
VIH	Input High Voltage	V <sub>CC</sub> -0.7	V <sub>CC</sub> -0.2	V	AC Coupled
V <sub>IL</sub>	Input Low Voltage	V <sub>CC</sub> -0.7	V <sub>CC</sub> -0.2	V	AC Coupled
VIH	Input High Current	-250	200	μΑ	
V <sub>IL</sub>	Input Low Current	-200	200	μΑ	



Table 5. Absolute Maximum Ratings1

Parameter	Min	Тур	Max	Units
TTL Power Supply Voltage (V <sub>CC</sub> )	0.5		+4	V
PECL DC Input Voltage (V <sub>INP</sub> )	-0.5		V <sub>CC</sub> +0.5	V
TTL DC Input Voltage (V <sub>INP</sub> )	-0.5		5.5	V
DC Voltage applied to outputs for High output state $(V_{IN\ TTL})$	-0.5		V <sub>CC</sub> +0.5	V
TTL Output Current (I <sub>OUT</sub> ) (DC, Output High)			50	mA
PECL Output Current (I <sub>OUT</sub> ) (DC, Output High)			50	mA
Case Temperature Under Bias (T <sub>C</sub> )	-55		125	°C
Storage Temperature (T <sub>STG</sub> )	-65		150	°C
Maximum Input	400	1K	1500	V

<sup>1.</sup> CAUTION: Stresses listed under "Absolute Maximum Ratings" may be applied to devices one at a time without causing permanent damage. Functionality at or above the values listed is not implied. Exposure to these values for extended periods may affect device reliability.

Table 6. Recommended Operating Conditions <sup>2</sup>

Parameter	Min	Тур	Max	Units
Power Supply Voltage (V <sub>DD</sub> )	+3.1		+3.5	V
Ambient Operating Temperature Range (T)	0		70	°C
ICC Current Supply		125	200	mA

<sup>2.</sup> AMCC guarantees the functional and parametric operation of the part under "Recommended Operating Conditions," except where specifically noted in the AC and DC Parametric Tables.

Figure 8. Output Circuit

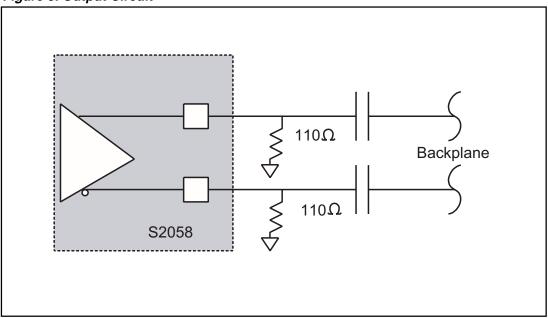
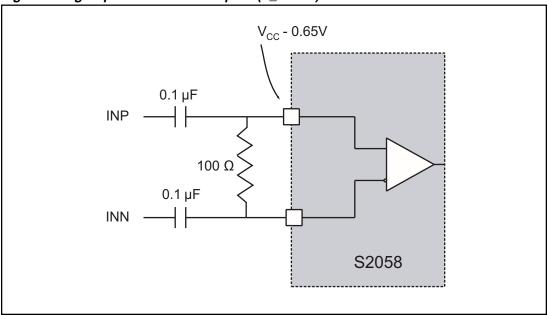


Figure 9. High Speed Differential Inputs (L\_Sin/IN)





### **Ordering Information**

Grade	Device	Package
S – Commercial/ Industrial	2058	A – 28-Pin SOIC



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